

#### **INFRA-RED EMITTING DIODES**

AP2012F3C AP2012SF4C

#### **Features**

- WATER CLEAR LENS AVAILABLE.
- •2.0mmx1.2mm SMT LED, 1.1mm THICKNESS.
- •HIGH POWER OUTPUT.
- •PACKAGE: 2000PCS/REEL.

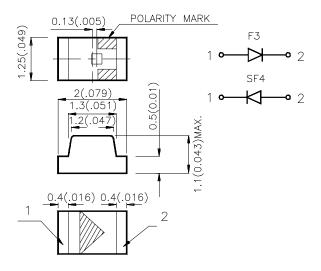
#### **Description**

F3 Made with Gallium Arsenide Infrared Emitting diodes.

SF4 Made with Gallium Aluminum Arsenide Infrared

Emitting diodes.

#### **Package Dimensions**



#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.1 (0.004\mbox{"})$  unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge package.
- 4. Specifications are subject to change without notice.

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#### **Selection Guide**

Part No.	Dice	Lens Type	<b>Po= (mW/sr)</b> @20mA		<b>Viewing</b> Angle
			Min.	Тур.	201/2
AP2012F3C	GaAs	WATER CLEAR	0.5	1.2	120°
AP2012SF4C	GaAlAs	WATER CLEAR	0.5	1	120°

#### Note:

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Item	P/N	Symbol	Тур.	Max.	Unit	Condition
Forward Voltage	F3 SF4	V <sub>F</sub>	1.2 1.3	1.5 1.7	V	IF=20mA
Reverse Current	F3 SF4	I <sub>R</sub>	-	10 10	uA	VR=5V
Junction Capacitance	F3 SF4	С	90 90	-	pF	V=0 f=1MHz
Peak Spectral Wavelength	F3 SF4	λР	940 880	-	nm	IF=20mA
Spectral Bandwidth	F3 SF4	Δλ	50 50	-	nm	IF=20mA

### Absolute Maximum Ratings at T<sub>A</sub>=25°C

ltem	Symbol	Maximum Rating	Units
Power Dissipation	P <sub>T</sub>	100	mW
Forward Current	I <sub>F</sub>	50	mA
Peak Forward Current	i <sub>FS</sub>	1.2	Α
Reverse Voltage	$V_R$	5	V
Operating Temperature	T <sub>A</sub>	-40~ +85	°C
Storage Temperature	T <sub>STG</sub>	-40~ +85	°C

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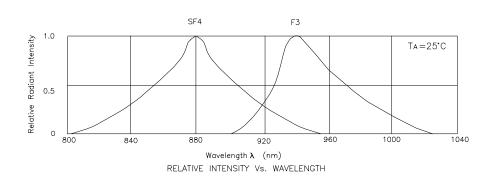
#### Note

1. 1/100 Duty Cycle, 10us Pluse Width.

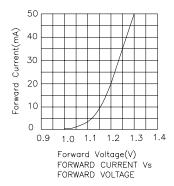
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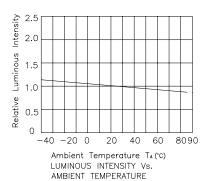
<sup>1.</sup>  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

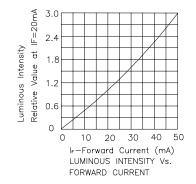


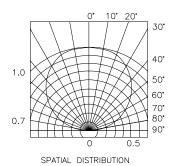


#### AP2012F3C









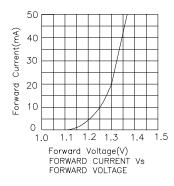
DATE: NOV/12/2001

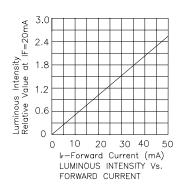
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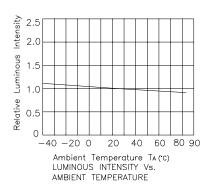
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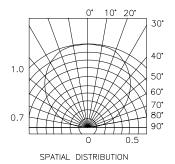
# Kingbright

#### AP2012SF4C



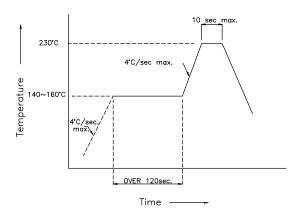






## AP2012F3C,AP2012SF4C SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



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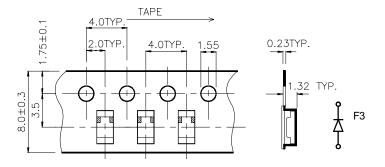
## Recommended Soldering Pattern

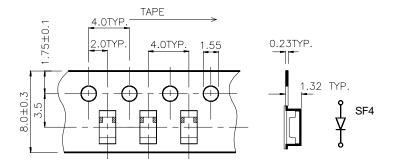
(Units : mm)



## **Tape Specifications**

(Units: mm)





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